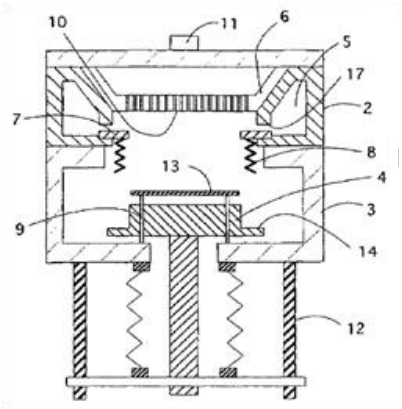


FIG. 1

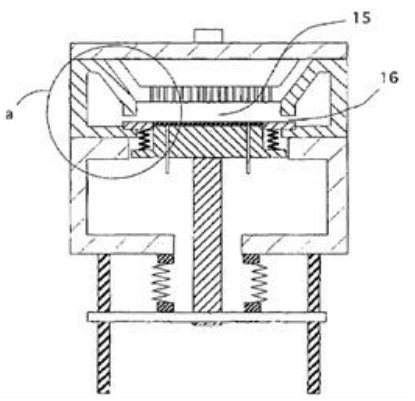


FIG. 2

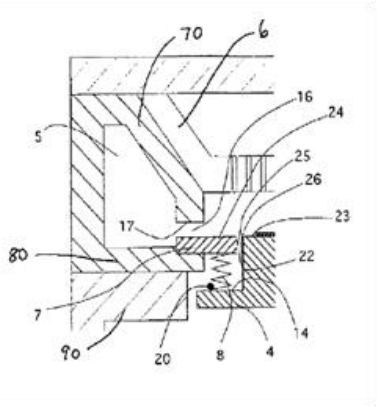


FIG. 3

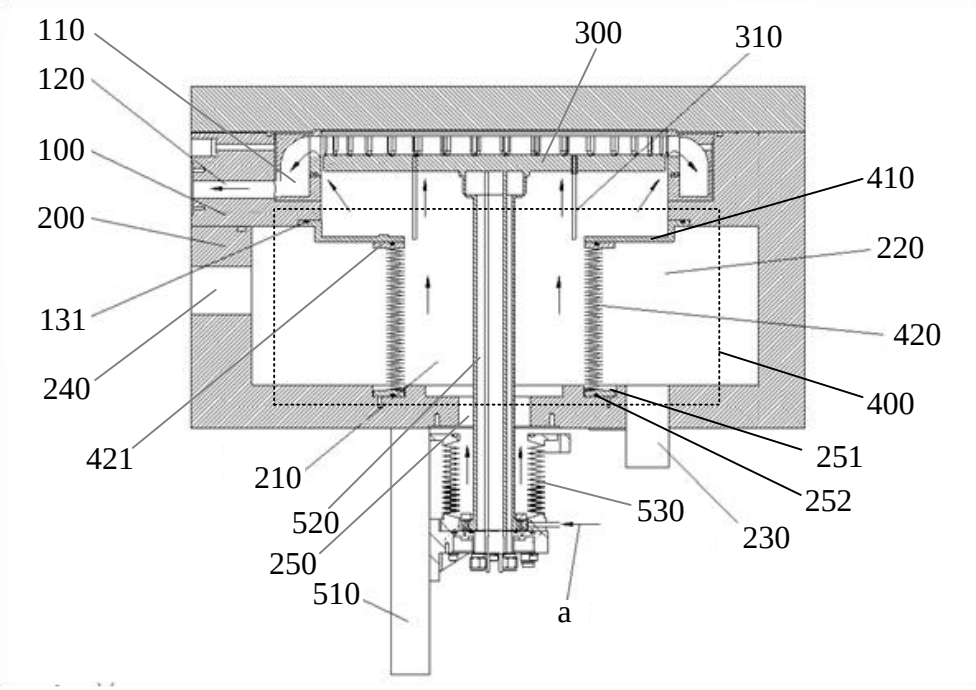

110
120
100
200
131
240
421
300
310
410
220
420
400
251
252
230
530
210
520
250
510
a

FIG. 4

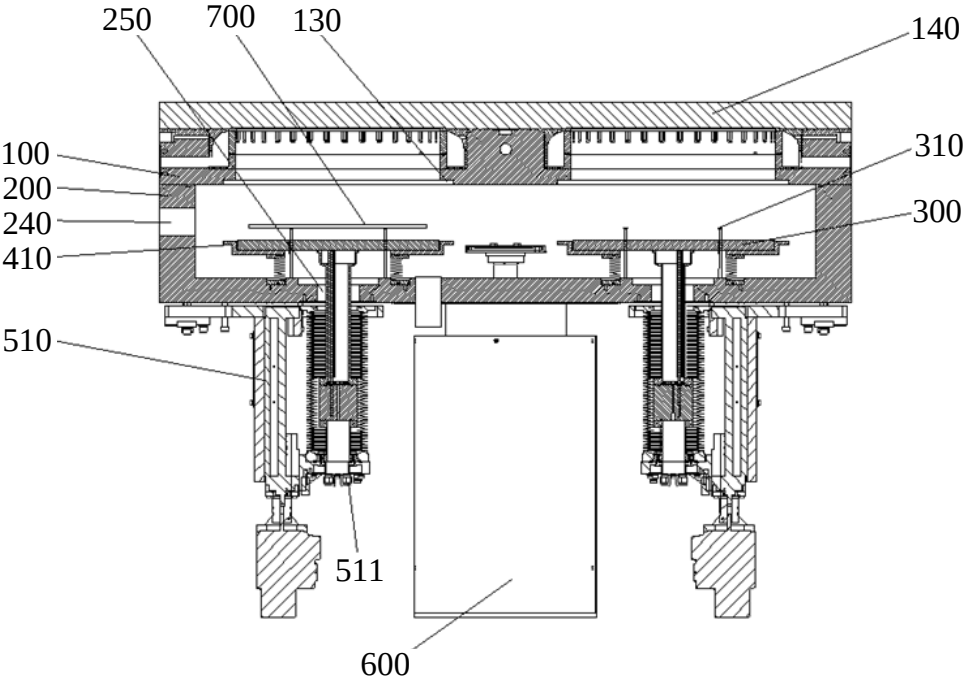

250
700
130
140
100
200
240
410
510
310
300
511
600

FIG. 5

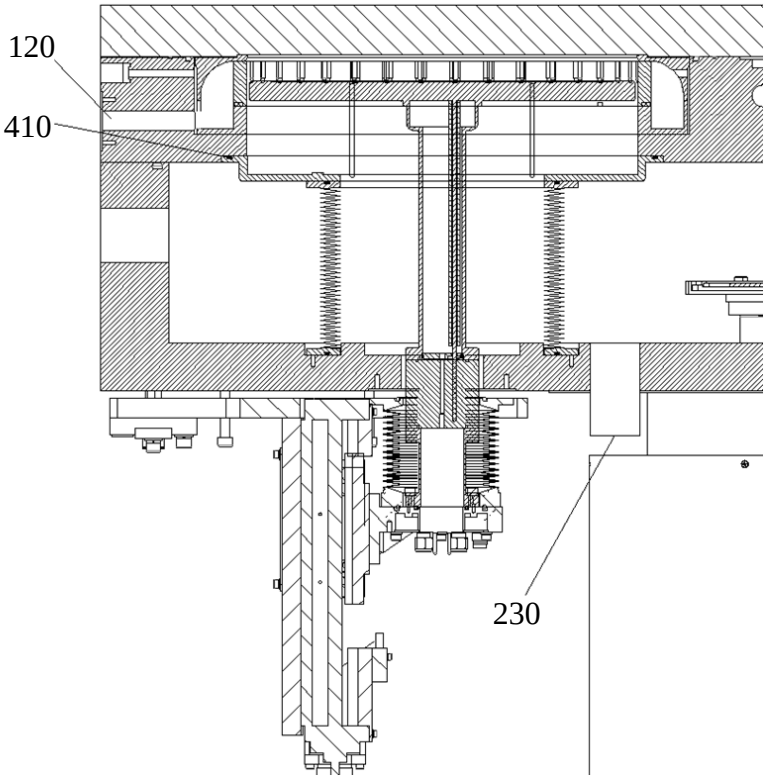


FIG. 6

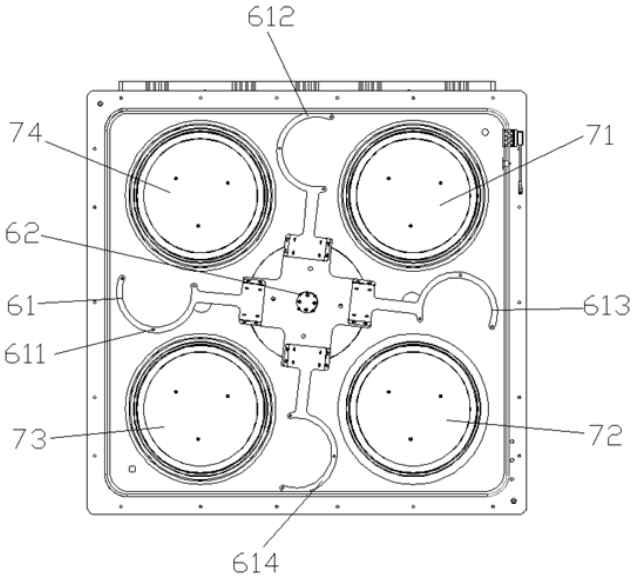


FIG. 7

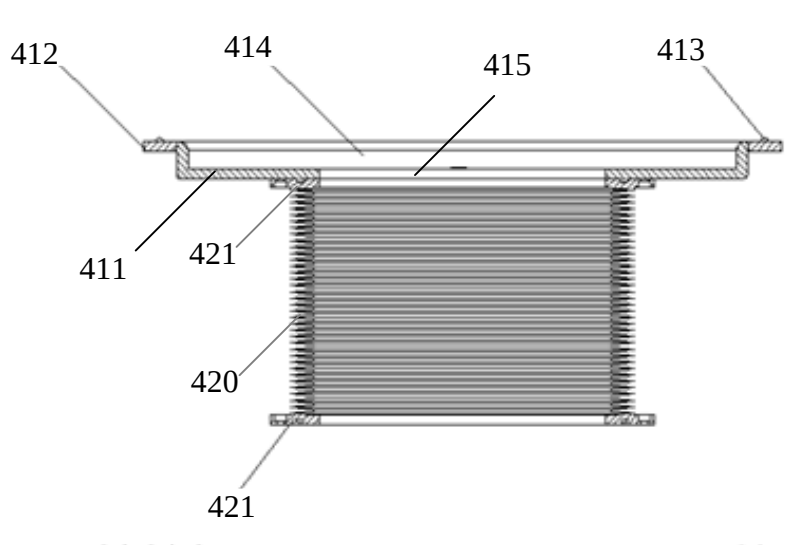

412
414
415
413
411
421
420
421

FIG. 8

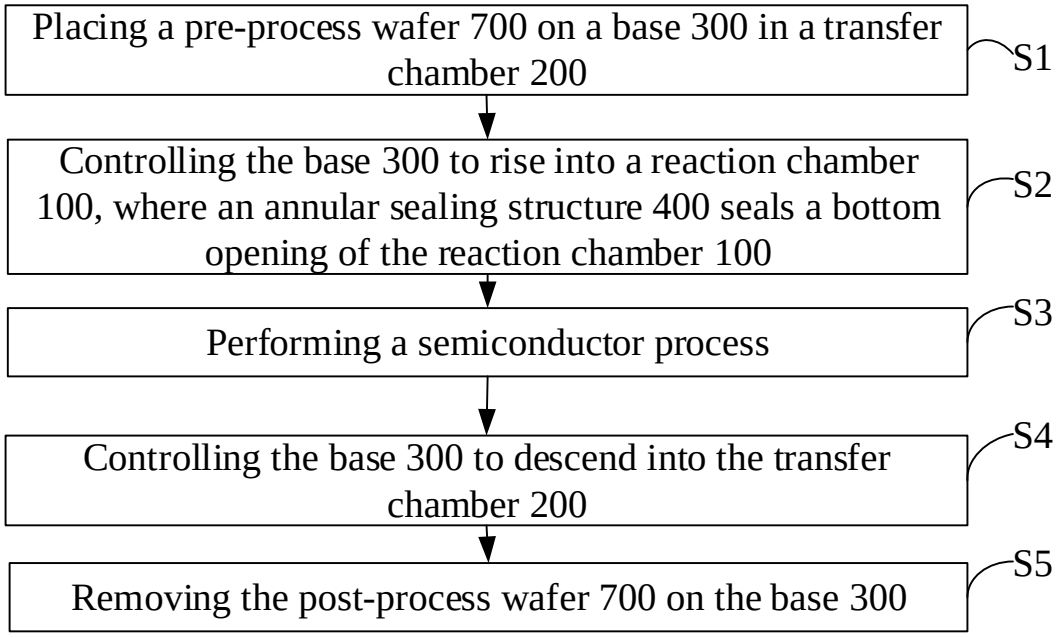

Placing a pre-process wafer 700 on a base 300 in a transfer chamber 200
S1
Controlling the base 300 to rise into a reaction chamber 100, where an annular sealing structure 400 seals a bottom opening of the reaction chamber 100
S2
Performing a semiconductor process
S3
Controlling the base 300 to descend into the transfer chamber 200
S4
Removing the post-process wafer 700 on the base 300
S5

FIG. 9

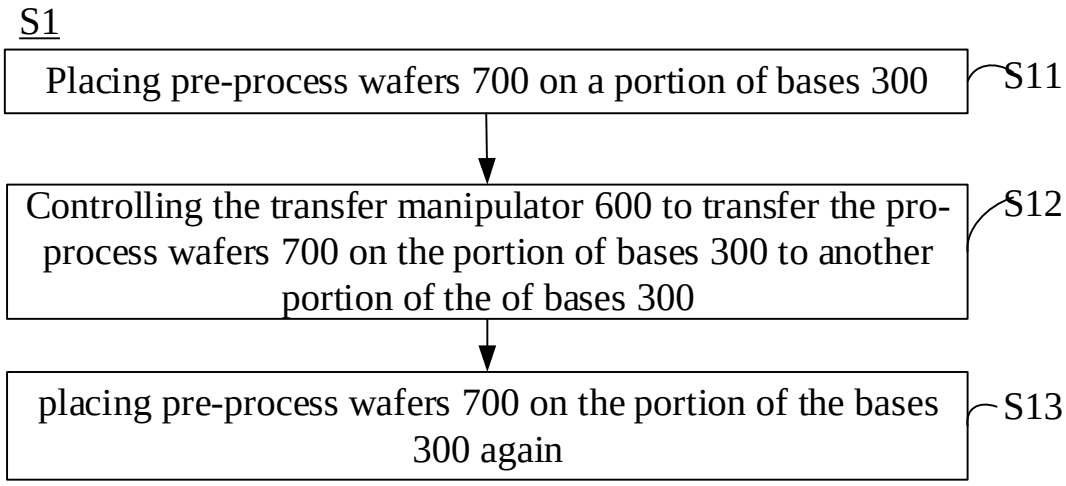

S1
Placing pre-process wafers 700 on a portion of bases 300
S11
Controlling the transfer manipulator 600 to transfer the pro-process wafers 700 on the portion of bases 300 to another portion of the of bases 300
S12
placing pre-process wafers 700 on the portion of the bases 300 again
S13

FIG. 10

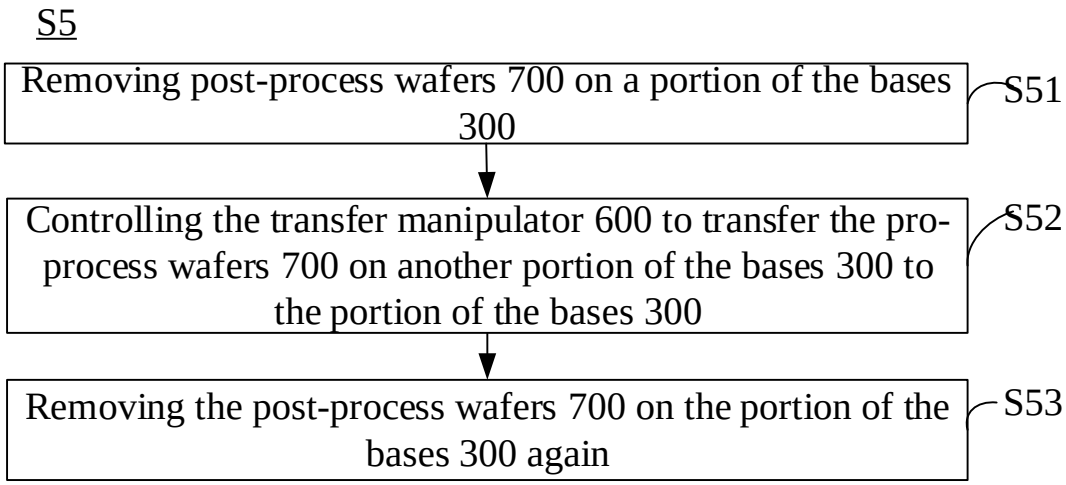

S5
Removing post-process wafers 700 on a portion of the bases 300
S51
Controlling the transfer manipulator 600 to transfer the pro-process wafers 700 on another portion of the bases 300 to the portion of the bases 300
S52
Removing the post-process wafers 700 on the portion of the bases 300 again
S53

FIG. 11